

IN THE CLAIMS:

The text of all pending claims, (including withdrawn claims) is set forth below. Cancelled and not entered claims are indicated with claim number and status only. The claims as listed below show added text with underlining and deleted text with ~~strikethrough~~. The status of each claim is indicated with one of (original), (currently amended), (cancelled), (withdrawn), (new), (previously presented), or (not entered).

Please CANCEL claims 1-4 and 12, and AMEND claim 5 in accordance with the following:

1-4. (Cancelled)

5. (Currently Amended) A drive chip integrated laser diode module comprising:
a laser diode module main body to generate and emit laser light;
a drive chip to drive the laser diode module main body; and
a main board having a plurality of lands to which leads of the drive chip are directly connected;

wherein the drive chip and the main board are integrally coupled with respect to the laser diode module main body,

the laser diode module main body comprises a laser diode inside the laser diode module main body and a plurality of laser diode leads protruding outwardly to apply electric power to the laser diode,

the drive chip is packaged with a mold resin in a state in which a semiconductor device is mounted on a lead frame, a plurality of coupling holes being formed in the mold resin of the drive chip, wherein the plurality of laser diode leads are respectively inserted into the coupling holes and a plurality of inner connectors are formed in each of the coupling holes, respectively, to which each of the laser diode leads are respectively electrically connected, the inner connectors having a predetermined shape in which end portions of the laser diode leads are inserted, and the drive chip further comprises a plurality of drive chip leads protruding outwardly from the mold resin.

6-9. (Cancelled)

10. (Previously Presented) The drive chip integrated laser diode module of claim 5, wherein the inner connectors are provided in the mold resin without protruding outwardly from the coupling holes.

11-13. (Cancelled)

14. (Original) The drive chip integrated laser diode module of claim 5, further comprising a through hole in the main body through which the laser diode module main body passes.

15. (Original) The drive chip integrated laser diode module of claim 5, wherein the main board is directly coupled to a surface of the drive chip so that the structure is made compact.

16-21. (Cancelled)